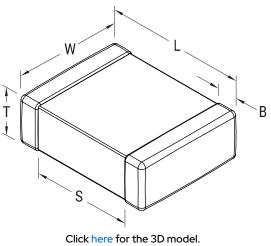


CKC33C333MWGAC7210

General Information

KC-LINK Comm COG, Ceramic, 0.033 uF, 20%, 650 VDC, COG, SMD, MLCC, Ultra-Stable, Low Loss, Class I, 3640, 6.3 mm





Series KC-LINK Comm COG Style SMD Chip Description SMD, MLCC, Ultra-Stable, Low Loss, Class I Features Ultra-Stable, Low Loss, Class I RoHS Yes Termination Tin Marking No AEC-Q200 No Typical Component Weight 790 mg Shelf Life 78 Weeks MSL 1			
Description SMD, MLCC, Ultra-Stable, Low Loss, Class I Features Ultra-Stable, Low Loss, Class I RoHS Yes Termination Tin Marking No AEC-Q200 No Typical Component Weight 790 mg Shelf Life 78 Weeks		Series	KC-LINK Comm COG
Loss, Class I Features Ultra-Stable, Low Loss, Class I RoHS Yes Termination Tin Marking No AEC-Q200 No Typical Component Weight 790 mg Shelf Life 78 Weeks		Style	SMD Chip
RoHS Yes Termination Tin Marking No AEC-Q200 No Typical Component Weight 790 mg Shelf Life 78 Weeks	3	Description	
Termination Tin Marking No AEC-Q200 No Typical Component Weight 790 mg Shelf Life 78 Weeks		Features	Ultra-Stable, Low Loss, Class I
Marking No AEC-Q200 No Typical Component Weight 790 mg Shelf Life 78 Weeks		RoHS	Yes
AEC-Q200 No Typical Component Weight 790 mg Shelf Life 78 Weeks		Termination	Tin
Typical Component Weight 790 mg Shelf Life 78 Weeks		Marking	No
Shelf Life 78 Weeks		AEC-Q200	No
		Typical Component Weight	790 mg
MSL 1		Shelf Life	78 Weeks
		MSL	1

Dimensions	
Chip Size	3640
L	9.3mm +/-0.6mm
W	10.2mm +/-0.4mm
Т	2mm +/-0.20mm
S	6.3mm MIN
В	1.27mm +/-0.4mm

Packaging Specifications	
Packaging	T&R, 330mm, Plastic Tape
Packaging Quantity	1000

Specifications	
Capacitance	0.033 uF
Measurement Condition	1 kHz 1.0Vrms
Tolerance	20%
Voltage DC	650 VDC
Dielectric Withstanding Voltage	845 VDC
Temperature Range	-55/+150°C
Temp. Coefficient	COG
Capacitance Change with Reference to +25°C and 0 VDC Applied (TCC)	30 ppm/C, 1kHz 1.0Vrms
Dissipation Factor	0.1% 1 kHz 1.0Vrms
Aging Rate	0% Loss/Decade Hour
Insulation Resistance	30.303 GOhms

Statements of suitability for certain applications are based on our knowledge of typical operating conditions for such applications, but are not intended to constitute - and we specifically disclaim - any warranty concerning suitability for a specific customer application or use. This Information is intended for use only by customers who have the requisite experience and capability to determine the correct products for their application. Any technical advice inferred from this Information or otherwise provided by us with reference to the use of our products is given gratis, and we assume no obligation or liability for the advice given or results obtained.

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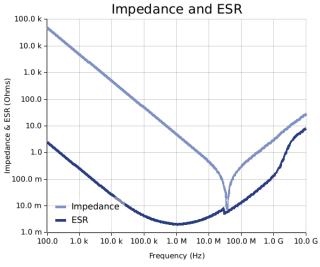


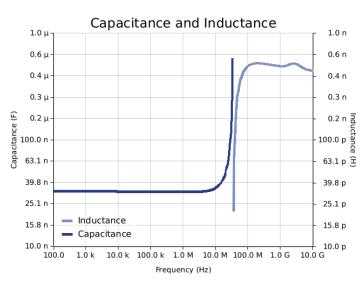


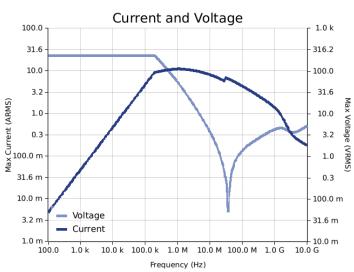
KC-LINK Comm COG, Ceramic, 0.033 uF, 20%, 650 VDC, COG, SMD, MLCC, Ultra-Stable, Low Loss, Class I, 3640, 6.3 mm

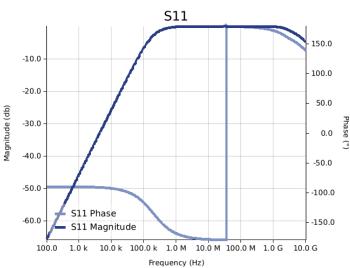
Simulations

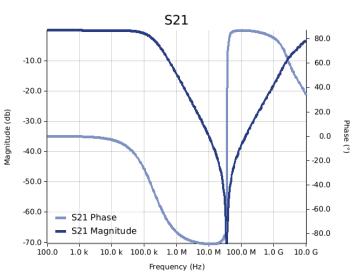
For the complete simulation environment please visit K-SIM.











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KC-LINK Comm COG, Ceramic, 0.033 uF, 20%, 650 VDC, COG, SMD, MLCC, Ultra-Stable, Low Loss, Class I, 3640, 6.3 mm

These are simulations.

This is not a specification!

The responses shown represent the typical response for each part type. Specific responses may vary, depending on manufacturing variation affects of all parameters involved, including the specified tolerances applied to capacitance and unspecified variations of ESR, ESL, and leakage resistance.

The responses shown do not represent a specified or implied maximum capability of the device for all applications.

- The ESR used for ripple "Ripple Current/Voltage vs. Frequency" plots is the ESR at ambient temperature.

- The ESR used for ripple Ripple Currenty votage vs. rrequency plots is unleast at an interact temperature.
 The ESR in the "Temperature Rise vs. Ripple Current" plots is adjusted to each incremental temperature rise before the power and ripple current is calculated.
 The effects shown herein are based on measured data from a multiple part sample of the parts in question.
 Ripple capability of this device will be factored by thermal resistance (Rth) created by circuit traces (addi affects of all parameters involved, including the specified tolerances applied to capacitance and unspecified variations of ESR, ESL, and leakage resistance.
 The peak voltages generated in the "Temperature Rise vs. Combined Ripple Currents" plot are calculated for each frequency and are not combined with voltages
- generated at any other harmonics.

 Please consult with the catalog or field applications engineer for maximum capability of the device in specific applications.

All product information and data (collectively, the "Information") are subject to change without notice.

KEMET K-SIM is designed to simulate behavior of components with respect to frequency, ambient temperature, and DC bias levels. The responses shown represent the typical response for each part type. Specific responses may vary, depending on manufacturing variation effects of all parameters involved, including the specified tolerances applied to capacitance and unspecified variations of ESR, ESL, and leakage resistance.

All Information given herein is believed to be accurate and reliable, but is presented without guarantee, warranty, or responsibility of any kind, expressed or implied. Statements of suitability for certain applications are based on our knowledge of typical operating conditions for such applications, but are not intended to constitute – and we specifically disclaim – any warranty concerning suitability for a specific customer application or use. This Information is intended for use only by customers who have the requisite experience and capability to determine the correct products for their application. Any technical advice inferred from this Information or otherwise provided by us with reference to the use of our products is given gratis, and we assume no obligation or liability for the advice given or results obtained.

If you have any questions please contact K-SIM.

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